

4220265/A 05/2017

NOTES:

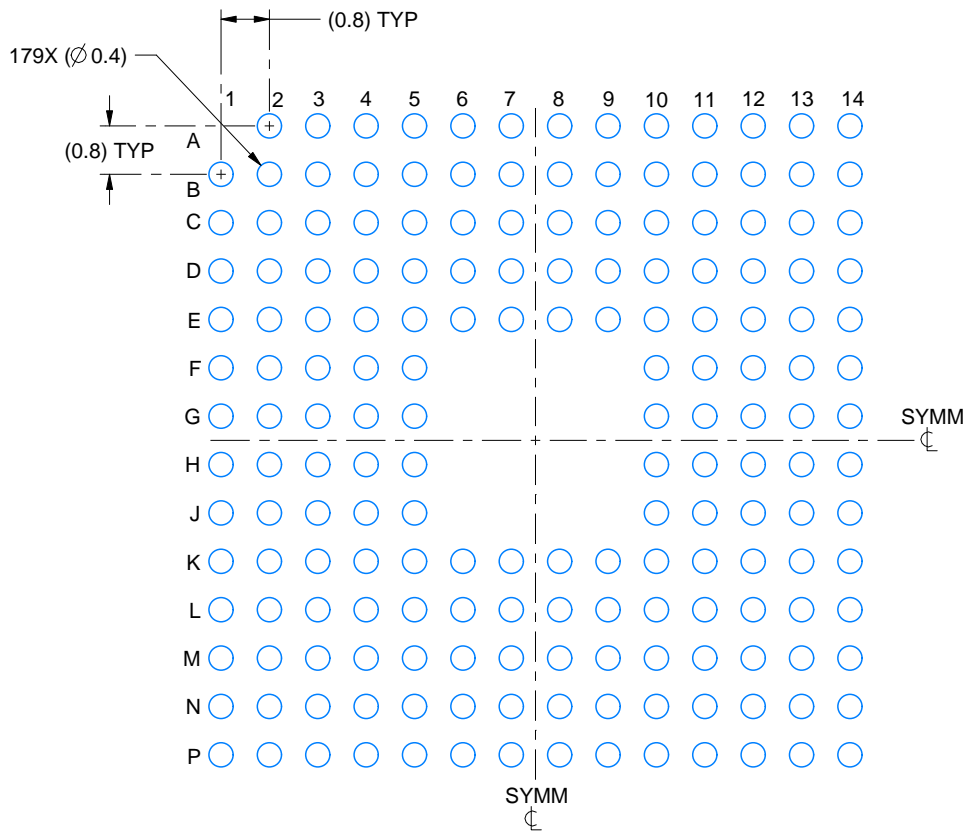
1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This is a Pb-free solder ball design.

EXAMPLE BOARD LAYOUT

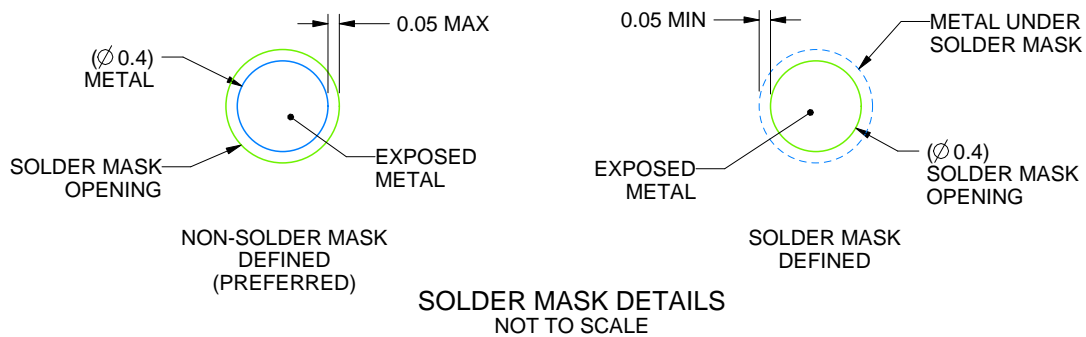
ZHH0179A

UBGA - 1.4 mm max height

BALL GRID ARRAY



LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE: 8X



SOLDER MASK DETAILS
NOT TO SCALE

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NOTES: (continued)

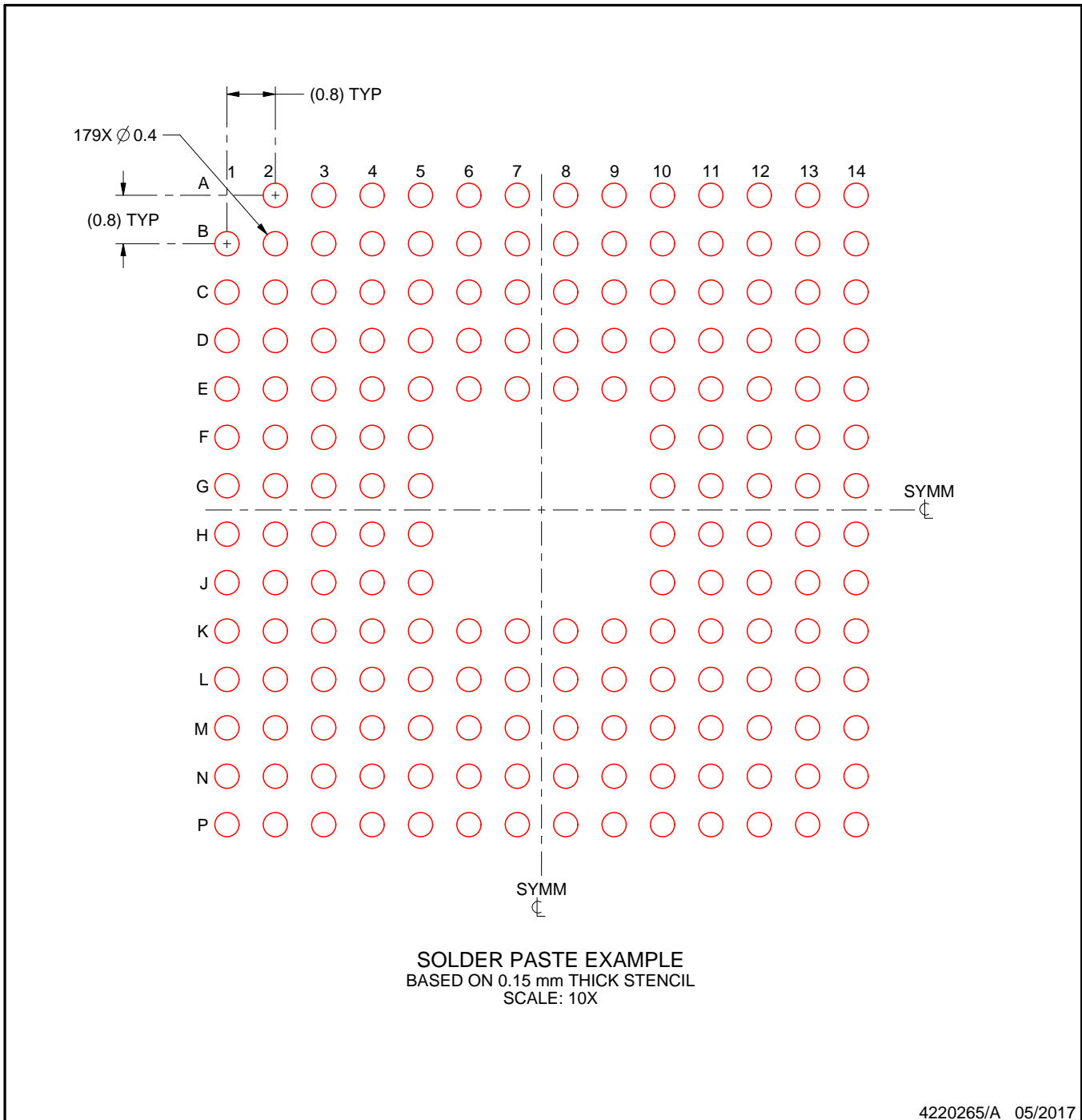
- Final dimensions may vary due to manufacturing tolerance considerations and also routing constraints. See Texas Instruments Literature No. SSZA002 (www.ti.com/lit/ssza002).

EXAMPLE STENCIL DESIGN

ZHH0179A

UBGA - 1.4 mm max height

BALL GRID ARRAY



NOTES: (continued)

5. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release.

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Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265
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